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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10007304	12/05/2001	438	629	2842	FAHMY

****APPLICANTS:** Kim Ki-Bum; Soininen Pekka; Raaijmakers Ivo;
28-5

****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
REPUBLIC OF KOREA 10-2000-0074025 12/06/2000

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO ASMMC.033AUS
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		
Verified and Acknowledged Examiners's initials		
TITLE : Copper interconnect structure having stuffed diffusion barrier		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for 0.0
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL		PREPARED F R ISSUE	
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